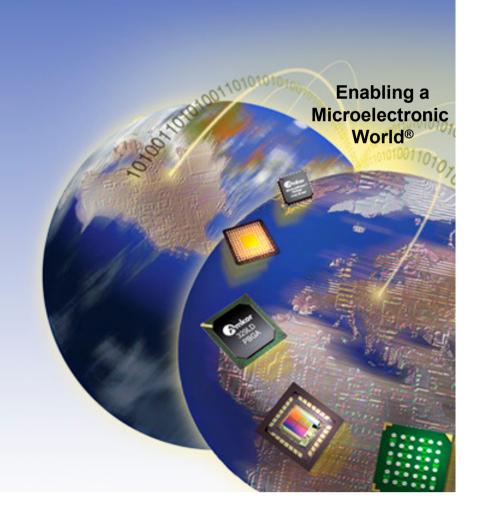
PLM Best Practice Conference

20^{th.} May '09, DPARK, Director, Corporate R&D, Amkor Technology Korea

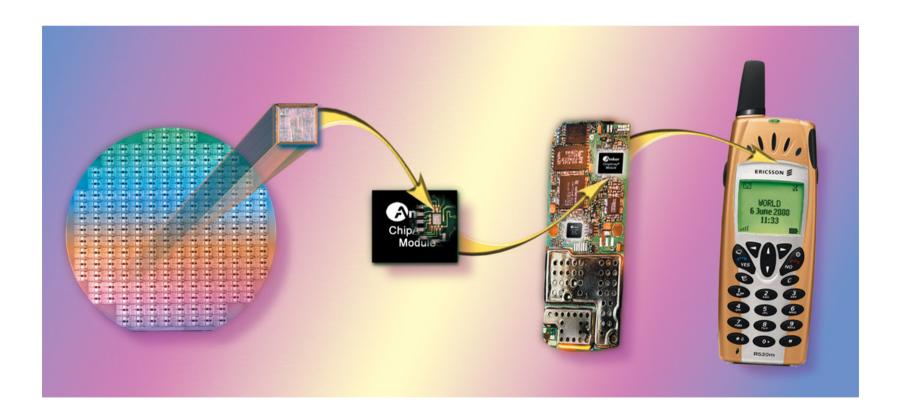




What is Package?

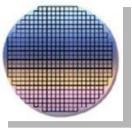


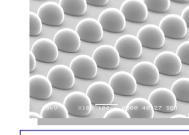
Connecting Silicon to Real World



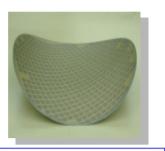
Package Assembly & Test Process flow













0. Wafer Fab

1. Solder Bumping

2. Wafer Test

3. Wafer Thinning

4. Sawing

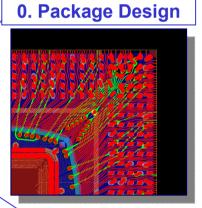
10. Final Test



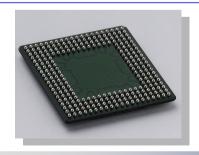
Multi Chip CSP

WB FC

FC CSP 단면도



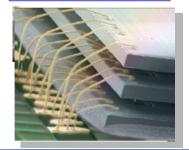
9. Solder Ball Attach



8. Molding



7. Die Stacking



6. Wire Bonding

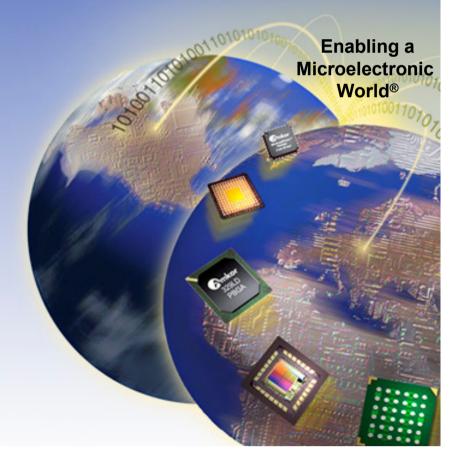


5. Die Attach



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System for Amkor's Operation Structure





Business Organization and Location



Major Sales Office and Manufacturing Sites



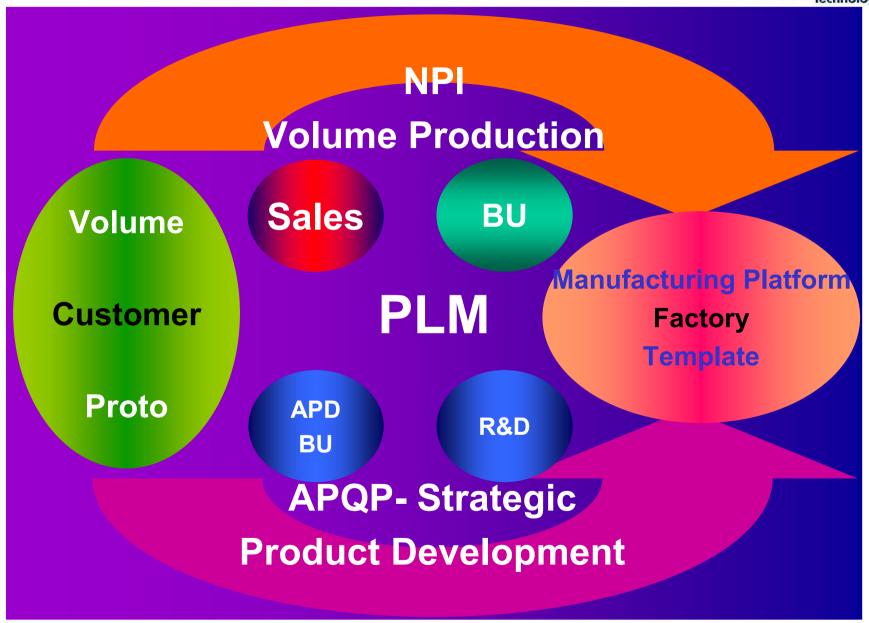
- Customer
- Head Quarter
- Sales/ Marketing

- Customer
- Sales

- Customer
- Sales
- R&D
- Factory
- Supplier

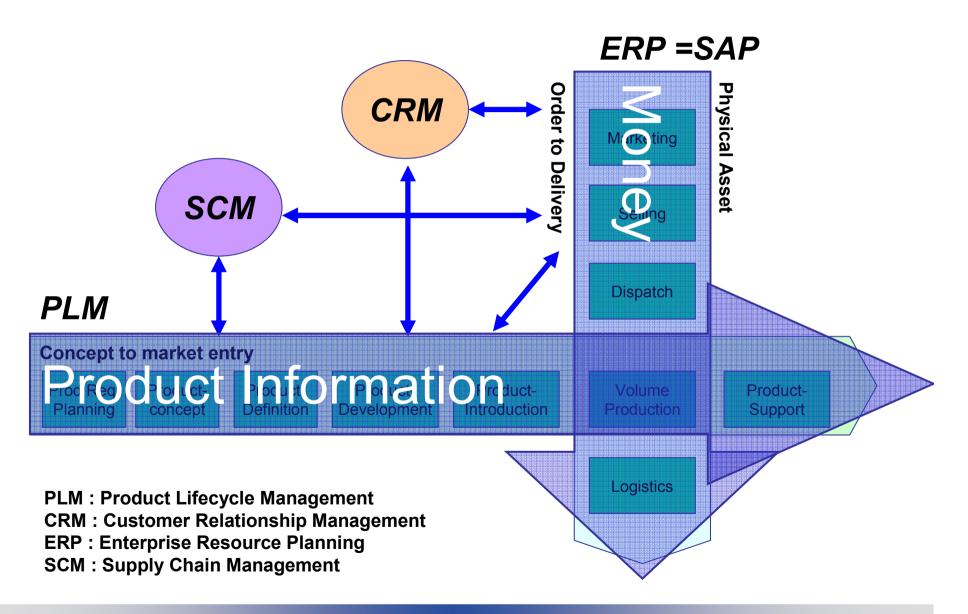
Simplified Amkor Biz Flow ...





What is PLM (Product Lifecycle Management)?

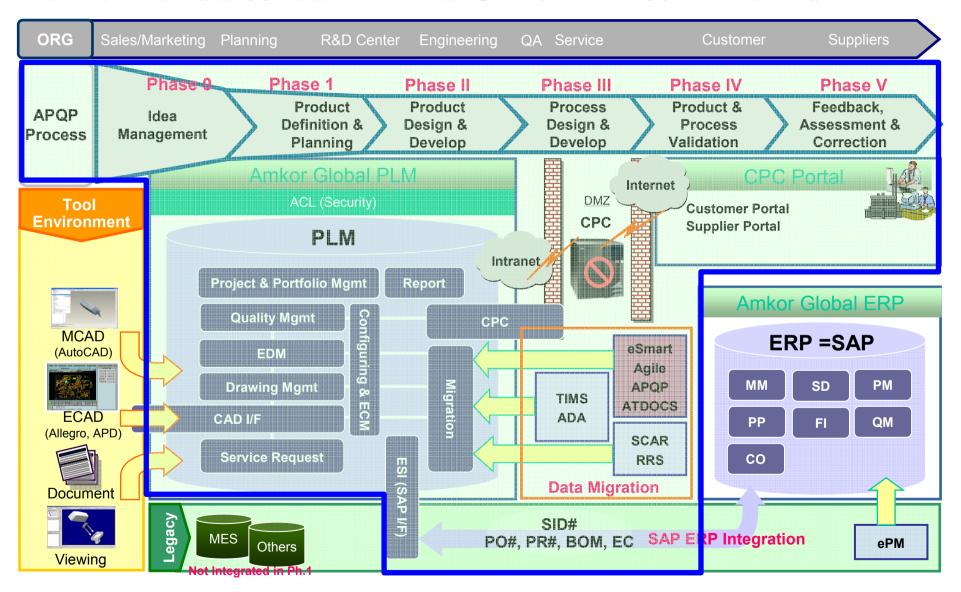




PLM (Product Life Cycle Management) 구축

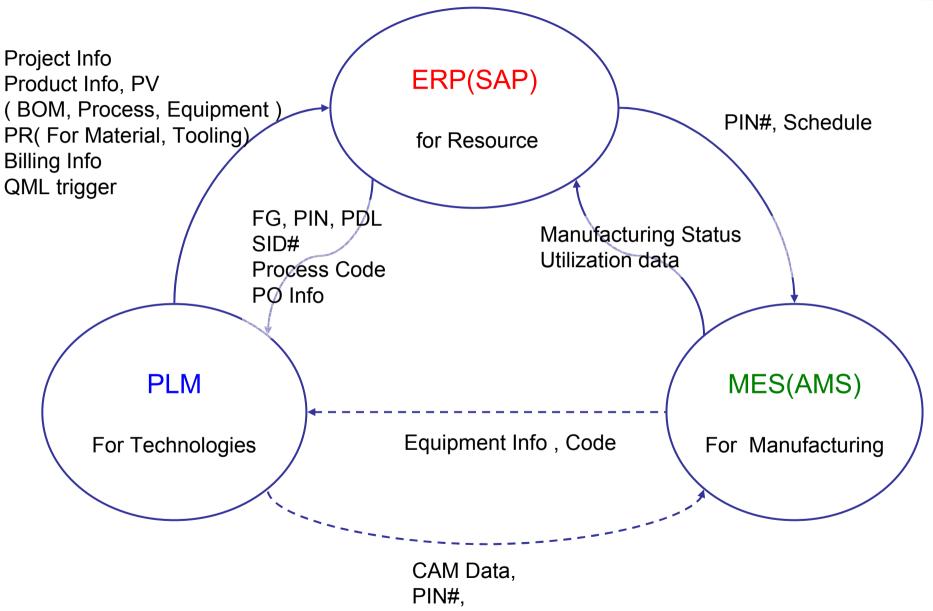


기존의 연구 개발 및 기술 관련 DB를 통합하고 SAP 및 MES와 연계함



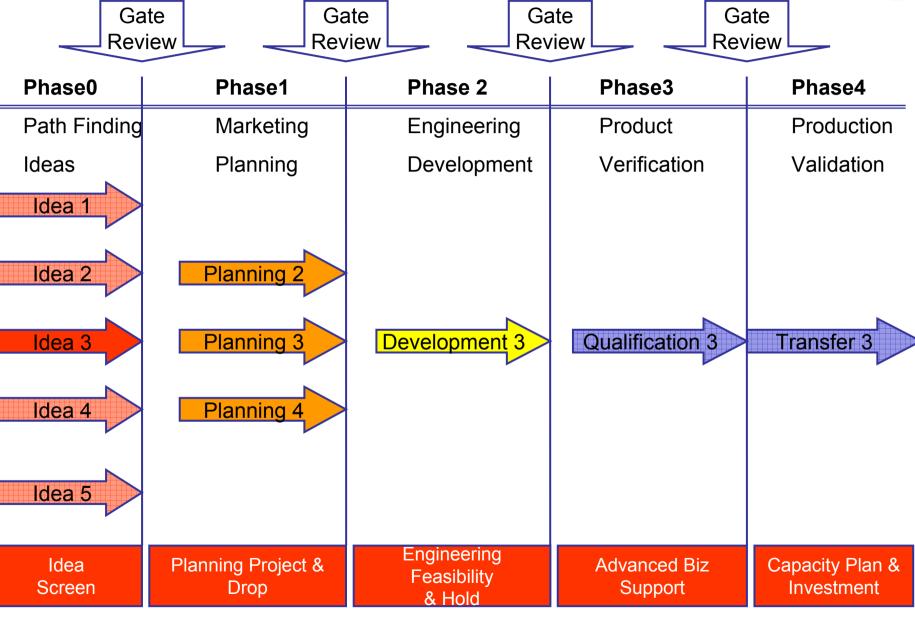
Major system categories for Amkor operation



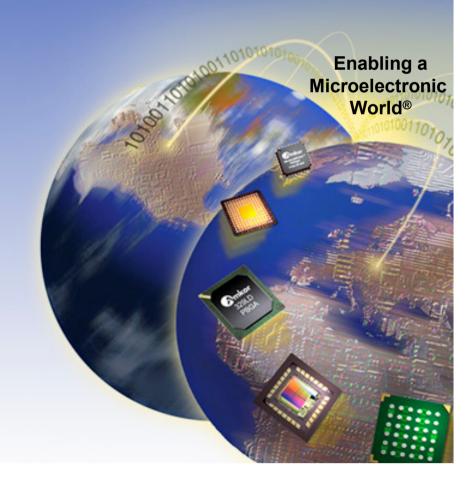


System for Idea & Development





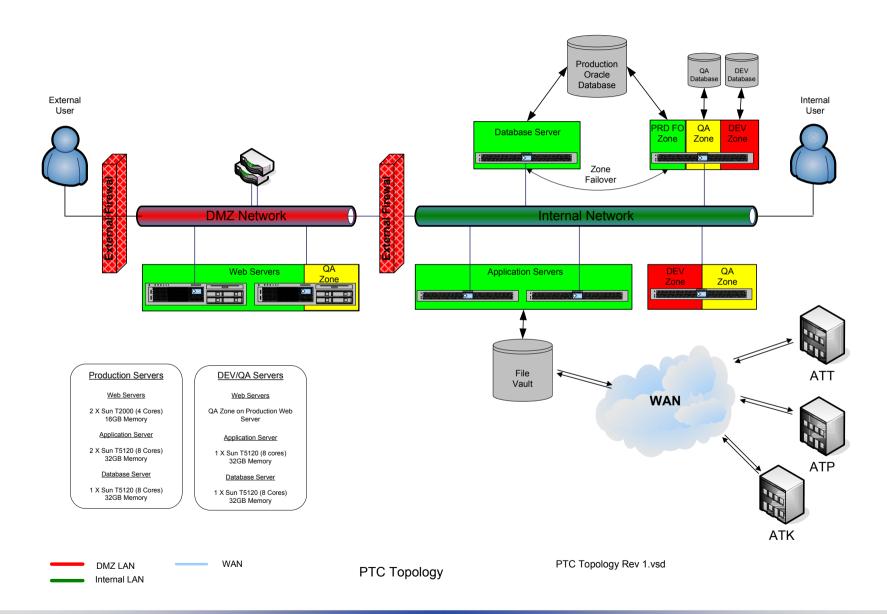
PLM Scope Overview





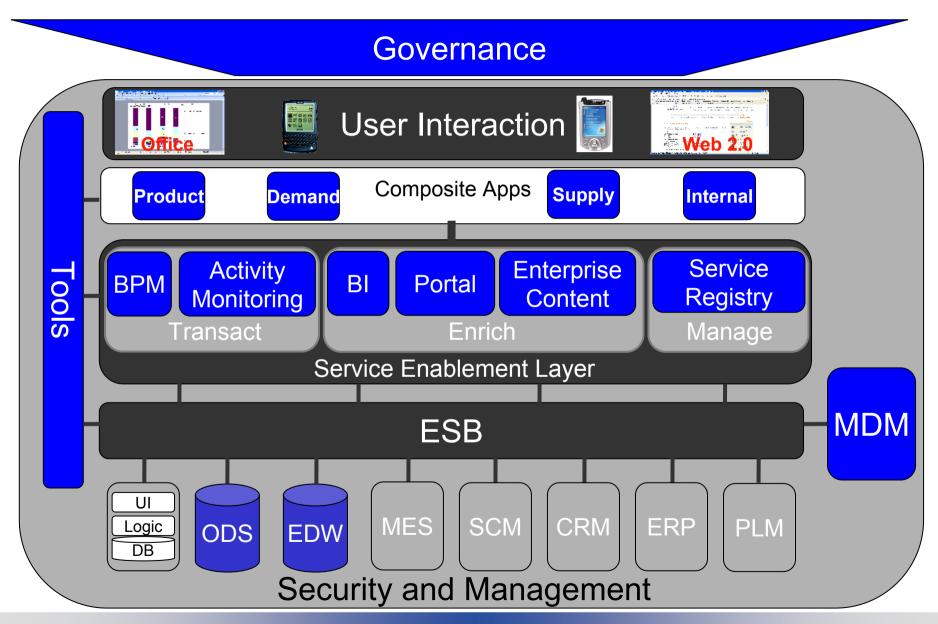
Amkor PLM Architecture





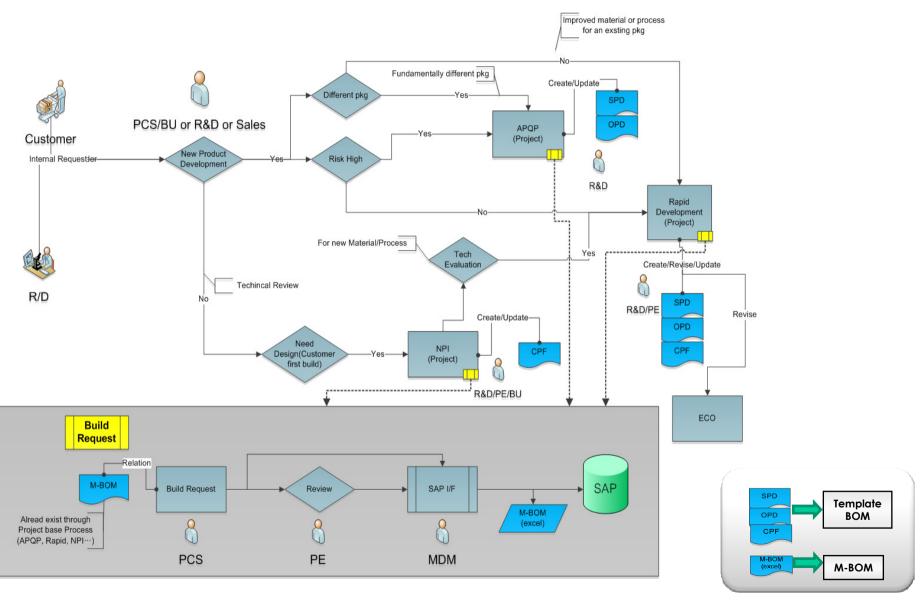
Enterprise SOA Framework





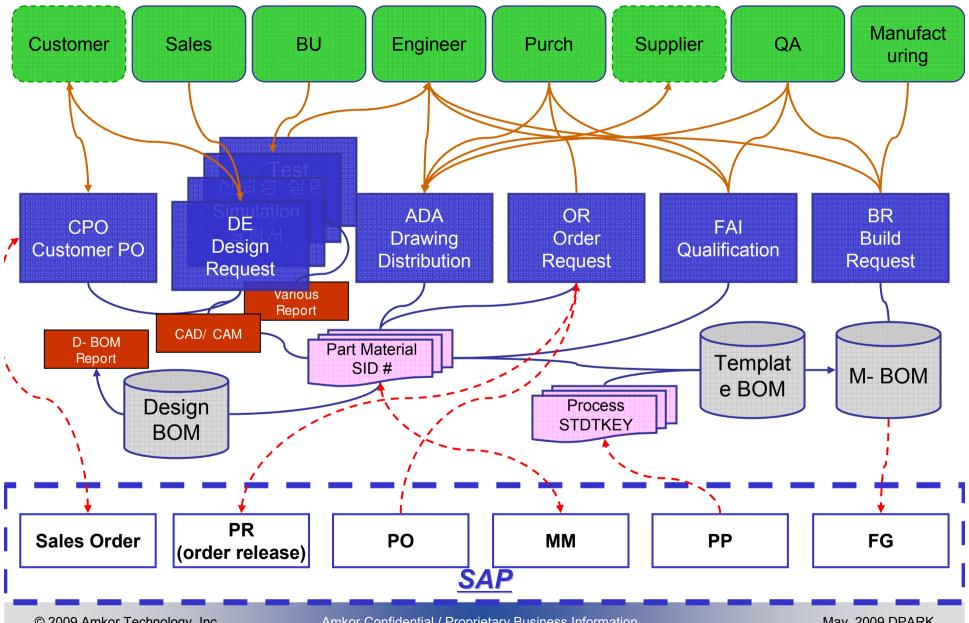
Overall BOM Process



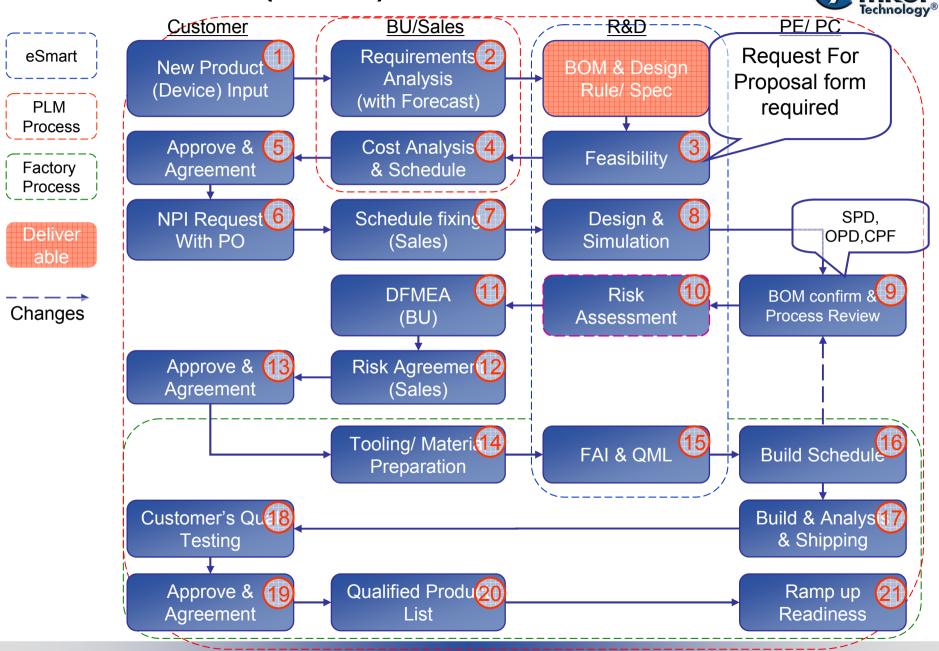


Team, Roles, Work Flows and Deliverables are linking with BOM



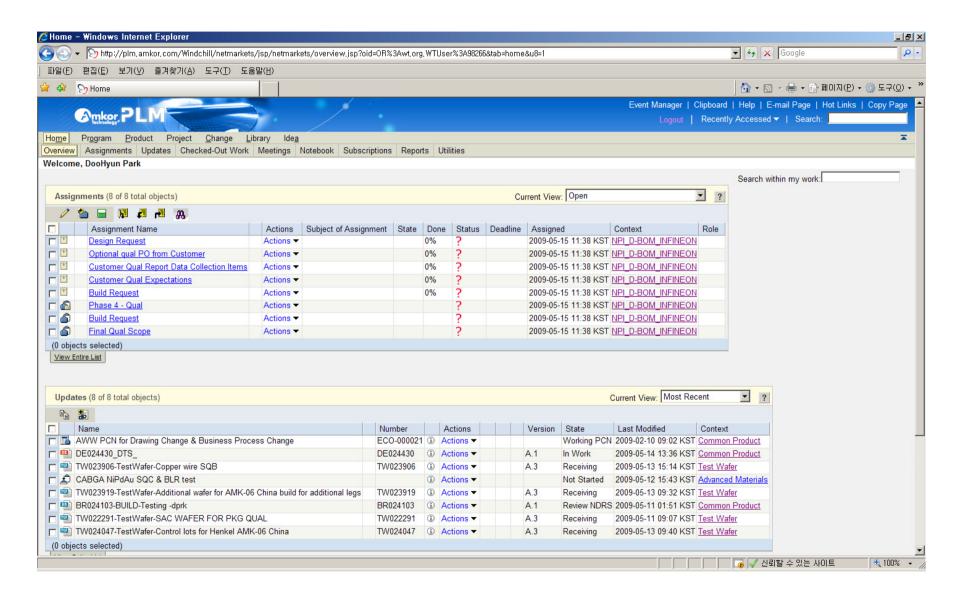


New Product (Device) Introduction



Amkor PLM UI





EPM Drawing View



